



#### 100V N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> T <sub>C</sub> = +25°C
400\/	8.8mΩ @ V <sub>GS</sub> = 10V	47A
100V	12.9mΩ @ V <sub>GS</sub> = 4.5V	39A

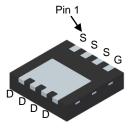
## **Description and Applications**

This new generation N-Channel Enhancement Mode MOSFET is designed to minimize  $R_{DS(ON)}$  and yet maintain superior switching performance. This device is ideal for use in notebook battery power management and loadswitch.

- Backlighting
- Power Management Functions
- DC-DC Converters







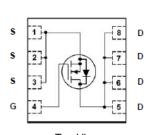
Bottom View

#### **Features and Benefits**

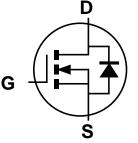
- 100% Unclamped Inductive Switch (UIS) Test in Production
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Mechanical Data**

- Case: V-DFN3333-8 (Type B)
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Below Diagram
- Terminals: Finish –NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.03 grams (Approximate)







**Equivalent Circuit** 

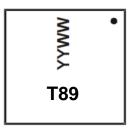
# Ordering Information (Note 4)

Part Number	Case	Packaging
DMT10H009LCG-7	V-DFN3333-8 (Type B)	2,000/Tape & Reel
DMT10H009LCG-13	V-DFN3333-8 (Type B)	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

### **Marking Information**



T89 = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 18 = 2018) WW = Week (01 to 53)

July 2018



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	100	V
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 6)	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	12.4 9.9	А
Continuous Drain Current, V <sub>GS</sub> = 10V	Steady State	$T_{C} = +25^{\circ}C$ $T_{C} = +70^{\circ}C$	I <sub>D</sub>	47 37	А
Maximum Continuous Body Diode Forward Current (Note 6)			Is	22	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	160	Α
Pulsed Body Diode Continuous Current (10µs Pulse, Duty Cycle = 1%)			I <sub>SM</sub>	160	Α
Avalanche Current, L = 0.3mH (Note 8)			I <sub>AS</sub>	21	Α
Avalanche Energy, L = 0.3mH (Note 8)			E <sub>AS</sub>	66	mJ

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

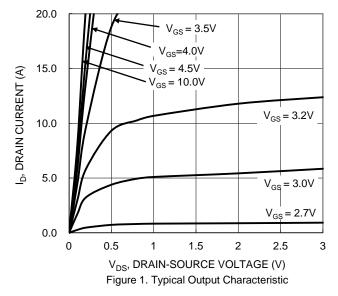
Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	$P_{D}$	1	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	129	°C/W
Total Power Dissipation (Note 6)	P <sub>D</sub>	2.1	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{ heta JA}$	59	°C/W
Thermal Resistance, Junction to Case	$R_{\theta JC}$	4.2	°C/W
Operating and Storage Temperature Range	$T_{J_1}T_{STG}$	-55 to +150	°C

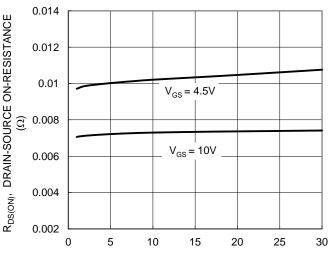
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	100	_	_	V	$V_{GS} = 0V$ , $I_D = 1mA$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	1	_	1	μΑ	$V_{DS} = 80V, V_{GS} = 0V$	
Gate-Source Leakage	Igss	1	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.1	I	2.5	٧	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance		1	7.2	8.8	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Diam-Source On-Resistance	R <sub>DS(ON)</sub>	1	9.8	12.9	mΩ	$V_{GS} = 4.5V, I_D = 5A$	
Diode Forward Voltage	$V_{SD}$	1	0.8	1.2	V	$V_{GS} = 0V, I_{S} = 20A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	2309	_		$V_{DS} = 50V$ , $V_{GS} = 0V$ f = 1MHz	
Output Capacitance	Coss	1	536	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>		13.7	_			
Gate Resistance	Rg	1	1.9	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge	Qq	_	20.2	_			
Gate-Source Charge	Qgs	_	7.0	_	nC	$V_{DD} = 50V, I_D = 20A,$	
Gate-Drain Charge	Q <sub>gd</sub>	_	8.5	_		$V_{GS} = 4.5V$	
Turn-On Delay Time	t <sub>D(ON)</sub>	-	5.4	_			
Turn-On Rise Time	t <sub>R</sub>	_	10.6	_	ns	$\begin{split} V_{DD} &= 50 \text{V}, \ V_{GS} = 10 \text{V}, \\ I_D &= 20 \text{A}, \ R_G = 3 \Omega \end{split}$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>		28.3	_			
Turn-Off Fall Time	t <sub>F</sub>	-	14.9	_			
Reverse Recovery Time	t <sub>RR</sub>	_	44.3	_	ns		
Reverse Recovery Charge	Q <sub>RR</sub>	_	65.5	_	nC	I <sub>F</sub> = 20A, di/dt = 100A/μs	

Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.







I<sub>D</sub>, DRAIN-SOURCE CURRENT (A) Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

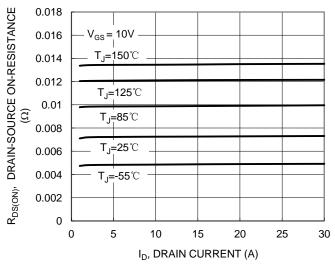


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

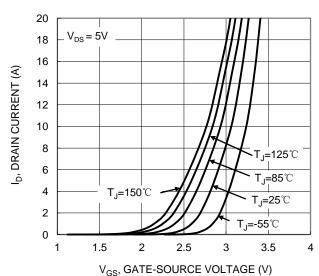
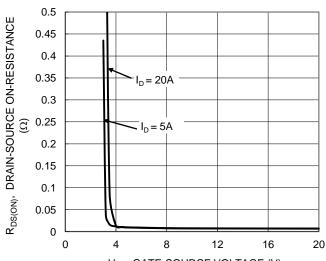


Figure 2. Typical Transfer Characteristic



V<sub>GS</sub>, GATE-SOURCE VOLTAGE (V) Figure 4. Typical Transfer Characteristic

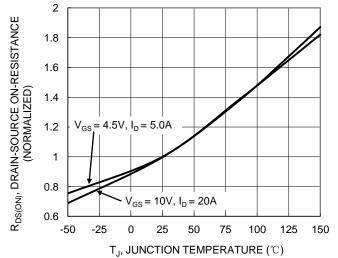


Figure 6. On-Resistance Variation with Junction Temperature





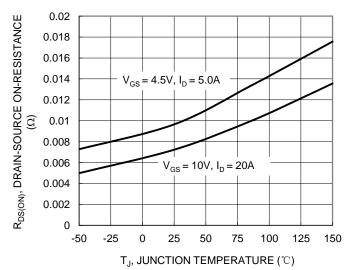


Figure 7. On-Resistance Variation with Junction Temperature

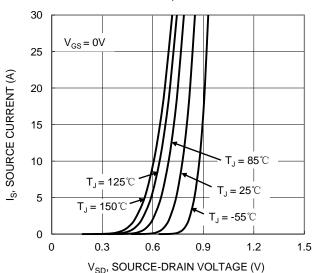


Figure 9. Diode Forward Voltage vs. Current

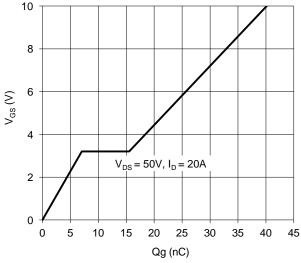


Figure 11. Gate Charge

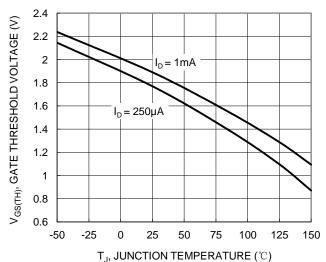
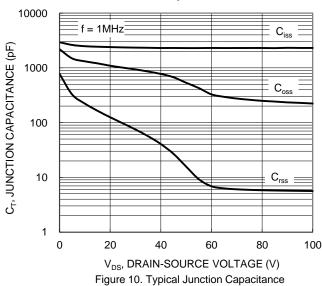


Figure 8. Gate Threshold Variation vs. Junction
Temperature



1000  $R_{DS(ON)}$  LIMITED P<sub>w</sub>=100μs 100 ID, DRAIN CURRENT (A) 10 P<sub>W</sub>=10n  $T_{J(MAX)}$ =150°C  $T_{C}$ =25°C Single Pulse DUT on infinite heatsink V<sub>GS</sub>=10V 0.1 0.1 10 100 1000 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V)

Figure 12. SOA, Safe Operation Area



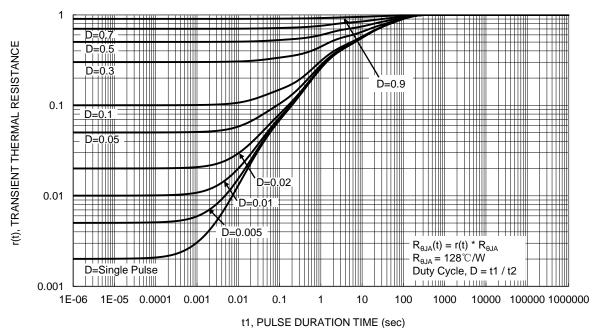


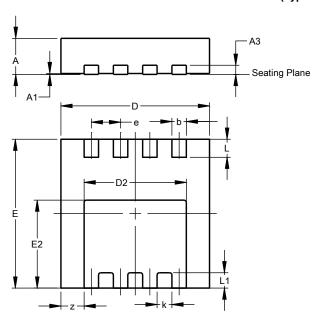
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### V-DFN3333-8 (Type B)

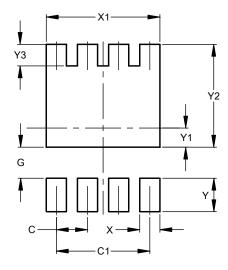


V-DFN3333-8 (Type B)					
Dim	Min	Max	Тур		
Α	0.75	0.85	0.80		
A1	0.00	0.05	0.02		
A3			0.203		
b	0.27	0.37	0.32		
D	3.25	3.35	3.30		
D2	2.17	2.37	2.27		
Е	3.25	3.35	3.30		
E2	1.85	2.05	1.95		
е	1		0.65		
k			0.33		
L	0.35	0.45	0.40		
L1			0.34		
Z	-		0.515		
All Dimensions in mm					

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### V-DFN3333-8 (Type B)



Dimensions	Value (in mm)		
С	0.650		
C1	1.950		
G	0.650		
X	0.420		
X1	2.370		
Υ	0.700		
Y1	0.400		
Y2	2.150		
Y3	0.450		



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